

Electronic Patent Application Fee Transmittal

Application Number:	10710662
Filing Date:	27-Jul-2004
Title of Invention:	[METHOD OF RELIEVING WAFER STRESS]
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Attorney Docket Number:	12336-US-PA
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Utility under 35 USC 111(a) Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1510	1510
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Total in USD (\$)				1810